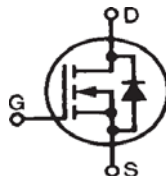


## High Voltage MOSFET

**IXTH20N50D**  
**IXTT20N50D**

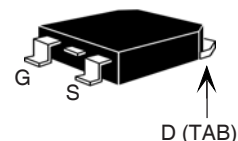
**N-Channel, Depletion Mode**

$$\begin{aligned} V_{DSX} &= 500V \\ I_{D25} &= 20A \\ R_{DS(on)} &\leq 330m\Omega \end{aligned}$$

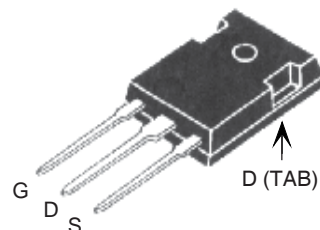


Symbol	Test Conditions	Maximum Ratings	
$V_{DSX}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	500	V
$V_{DGX}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}, R_{GS} = 1M\Omega$	500	V
$V_{GSX}$	Continuous	$\pm 30$	V
$V_{GSM}$	Transient	$\pm 40$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	20	A
$I_{DM}$	$T_C = 25^\circ\text{C}, \text{Pulse Width Limited by } T_{JM}$	50	A
$P_D$	$T_C = 25^\circ\text{C}$	400	W
$T_J$		- 55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		- 55 ... +150	$^\circ\text{C}$
$T_L$	1.6mm (0.062 in.) from Case for 10s	300	$^\circ\text{C}$
$T_{SOLD}$	Plastic Body for 10s	260	$^\circ\text{C}$
$M_d$	Mounting Torque (TO-247)	1.13 / 10	Nm/lb.in.
Weight	TO-268	4	g
	TO-247	6	g

TO-268 (IXTT)



TO-247 (IXTH)



G = Gate      D = Drain  
S = Source      TAB = Drain

### Features

- Normally ON Mode
- International Standard Packages
- Molding Epoxies Meet UL 94 V-0 Flammability Classification

### Advantages

- Easy to Mount
- Space Savings
- High Power Density

### Applications

- Level Shifting
- Triggers
- Solid State Relays
- Current Regulators
- Active Load

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSX}$	$V_{GS} = -10V, I_D = 250\mu A$	500		V
$V_{GS(off)}$	$V_{DS} = 25V, I_D = 250\mu A$	-1.5		- 3.5 V
$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100$ nA
$I_{DSS}$	$V_{DS} = V_{DSX}, V_{GS} = -10V$ $T_J = 125^\circ\text{C}$			25 $\mu A$ 500 $\mu A$
$R_{DS(on)}$	$V_{GS} = 10V, I_D = 10A, \text{ Note 1}$			330 m $\Omega$
$I_{D(on)}$	$V_{GS} = 0V, V_{DS} = 25V, \text{ Note 1}$		2.3	A

Symbol	Test Conditions	Characteristic Values		
	(T <sub>J</sub> = 25°C, Unless Otherwise Specified)	Min.	Typ.	Max.
<b>g<sub>fs</sub></b>	V <sub>DS</sub> = 30V, I <sub>D</sub> = 0.5 • I <sub>D25</sub> , Note 1	4.0	6.5	9.0 S
<b>C<sub>iss</sub></b>	V <sub>GS</sub> = -10V, V <sub>DS</sub> = 25V, f = 1MHz		6300	pF
<b>C<sub>oss</sub></b>			385	pF
<b>C<sub>rss</sub></b>			82	pF
<b>t<sub>d(on)</sub></b>	<b>Resistive Switching Times</b> V <sub>GS</sub> = -10V, V <sub>DS</sub> = 0.5 • V <sub>DSX</sub> , I <sub>D</sub> = 0.5 • I <sub>D25</sub> R <sub>G</sub> = 4.7Ω (External)		35	ns
<b>t<sub>r</sub></b>			85	ns
<b>t<sub>d(off)</sub></b>			110	ns
<b>t<sub>f</sub></b>			75	ns
<b>Q<sub>g(on)</sub></b>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 0.5 • V <sub>DSX</sub> , I <sub>D</sub> = 0.5 • I <sub>D25</sub>		78.5	nC
<b>Q<sub>gs</sub></b>			19.2	nC
<b>Q<sub>gd</sub></b>			35.0	nC
<b>R<sub>thJC</sub></b>			0.31	°C/W
<b>R<sub>thCS</sub></b>				°C/W

### Safe Operating Area Specification

Symbol	Test Conditions	Min.	Typ.	Max.
<b>SOA</b>	V <sub>DS</sub> = 400V, I <sub>D</sub> = 0.6A, T <sub>C</sub> = 75°C, t <sub>p</sub> = 3s	240		W

### Source-Drain Diode

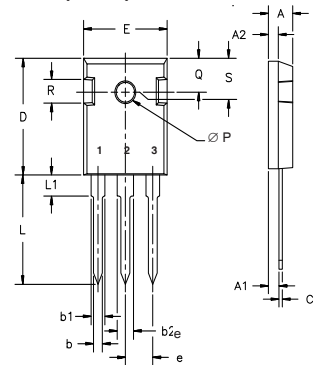
Symbol	Test Conditions	Characteristic Values		
	(T <sub>J</sub> = 25°C, Unless Otherwise Specified)	Min.	Typ.	Max.
<b>V<sub>SD</sub></b>	I <sub>F</sub> = I <sub>D25</sub> , V <sub>GS</sub> = -10V, Note 1	0.75	1.4	V
<b>t<sub>rr</sub></b>	I <sub>F</sub> = 20A, -di/dt = 100A/μs V <sub>R</sub> = 100V, V <sub>GS</sub> = -10V		590	ns
<b>I<sub>RM</sub></b>			32.6	A
<b>Q<sub>RM</sub></b>			9.6	μC

Note 1: Pulse Test, t ≤ 300μs; Duty Cycle, d ≤ 2%.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

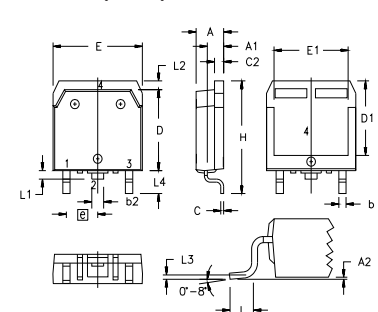
### TO-247 (IXTH) Outline



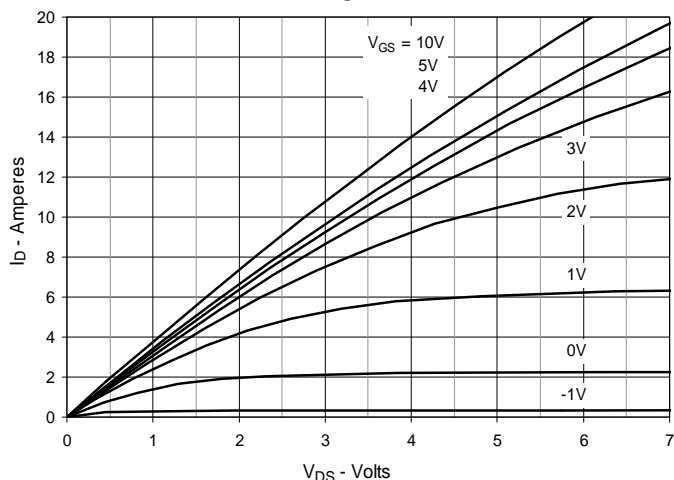
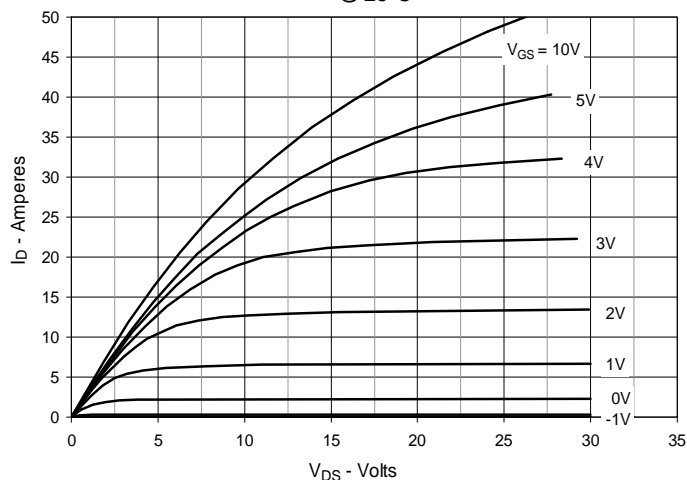
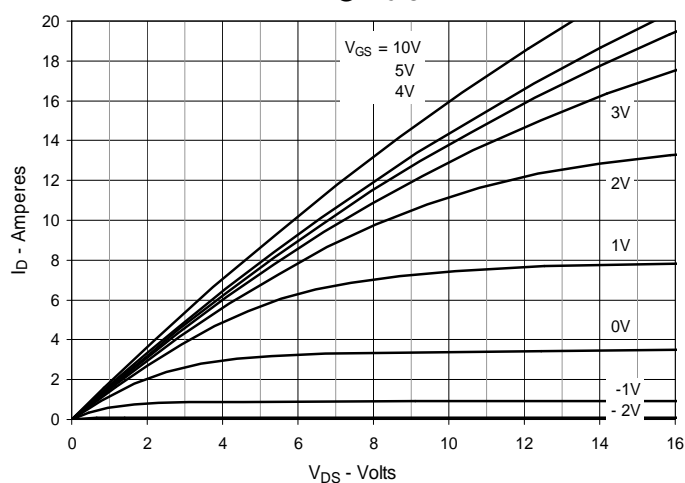
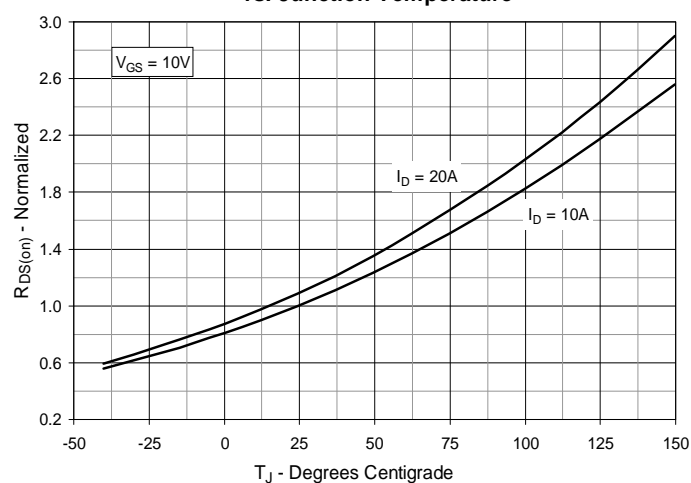
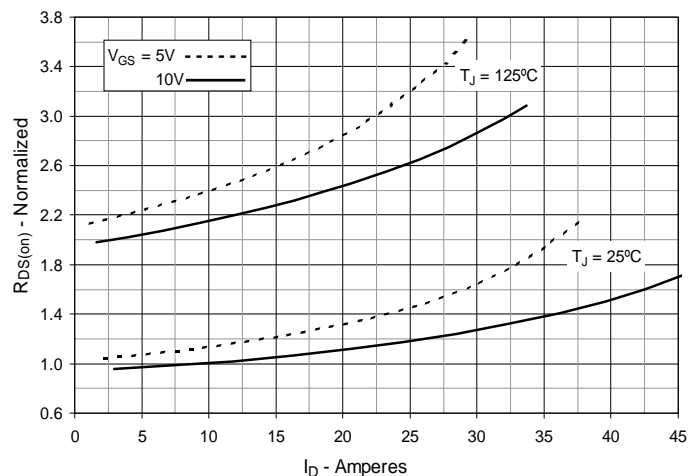
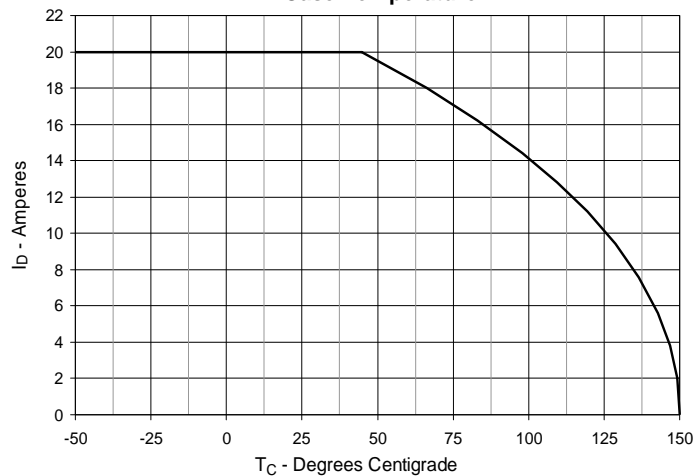
Terminals: 1 - Gate  
3 - Source  
2 - Drain  
Tab - Drain

Dim.	Millimeter	Inches
	Min.	Max.
A	4.7	5.3
A <sub>1</sub>	2.2	2.54
A <sub>2</sub>	2.2	2.6
b <sub>1</sub>	1.0	1.4
b <sub>2</sub>	1.65	2.13
C	.4	.8
D	20.80	21.46
E	15.75	16.26
e	5.20	5.72
L	19.81	20.32
L1		4.50
ØP	3.55	3.65
Q	5.89	6.40
R	4.32	5.49
S	6.15 BSC	242 BSC

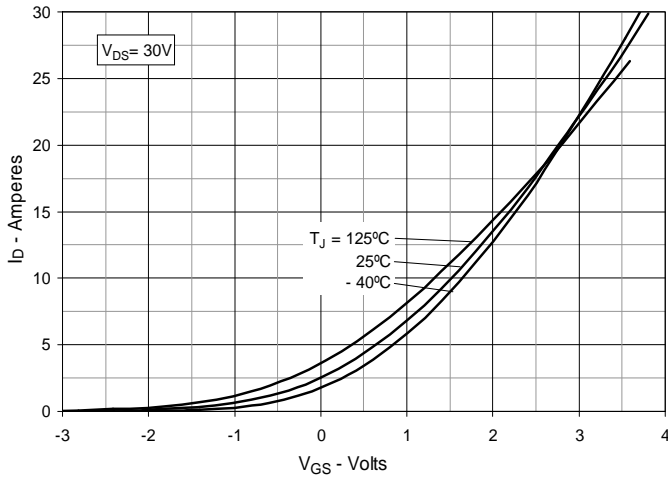
### TO-268 (IXTT) Outline



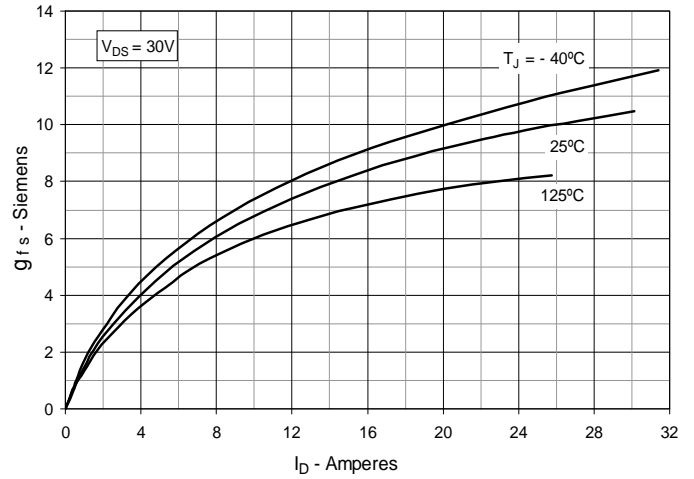
SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

**Fig. 1. Output Characteristics**  
**@ 25°C**

**Fig. 2. Extended Output Characteristics**  
**@ 25°C**

**Fig. 3. Output Characteristics**  
**@ 125°C**

**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 10A$  Value**  
**vs. Junction Temperature**

**Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 10A$  Value**  
**vs. Drain Current**

**Fig. 6. Maximum Drain Current vs.**  
**Case Temperature**


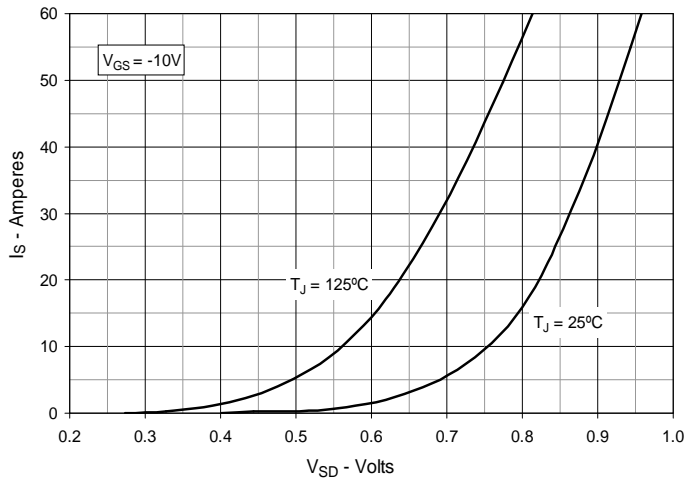
**Fig. 7. Input Admittance**



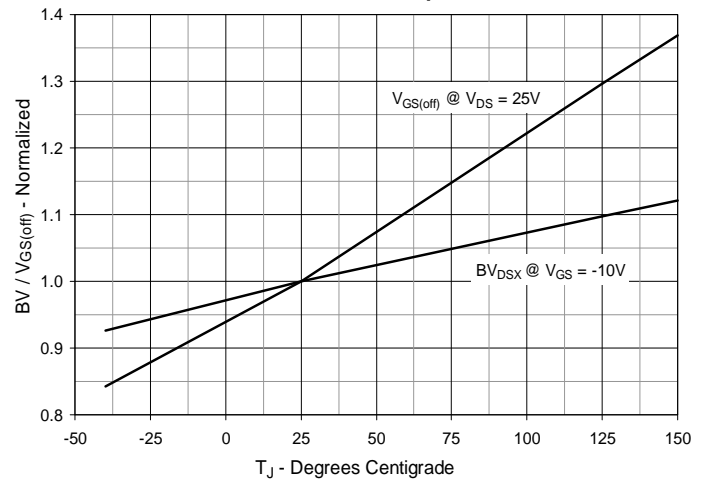
**Fig. 8. Transconductance**



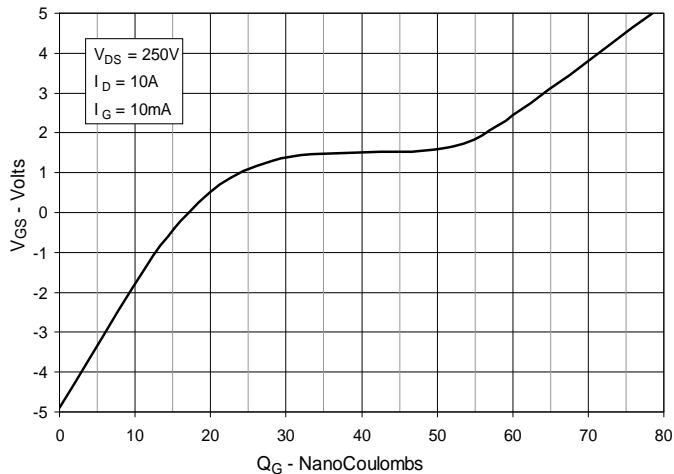
**Fig. 9. Forward Voltage Drop of Intrinsic Diode**



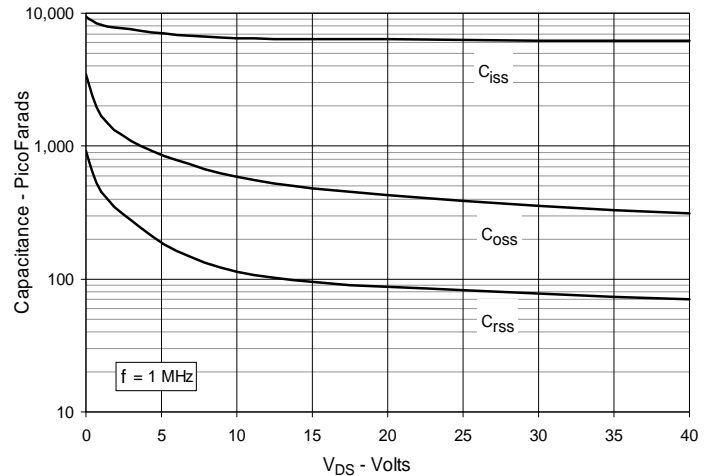
**Fig. 10. Breakdown and Threshold Voltages vs. Junction Temperature**



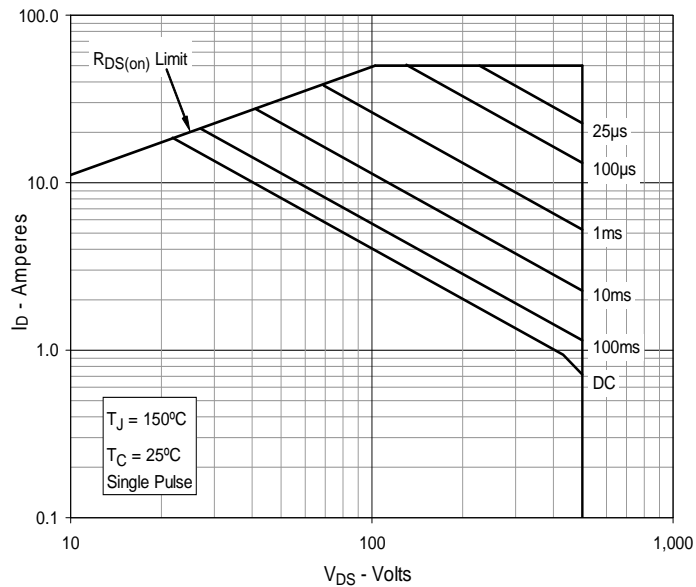
**Fig. 11. Gate Charge**



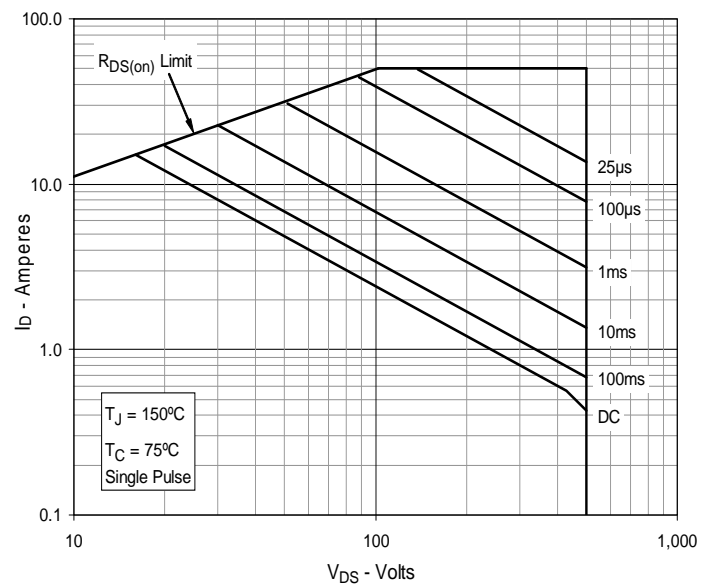
**Fig. 12. Capacitance**



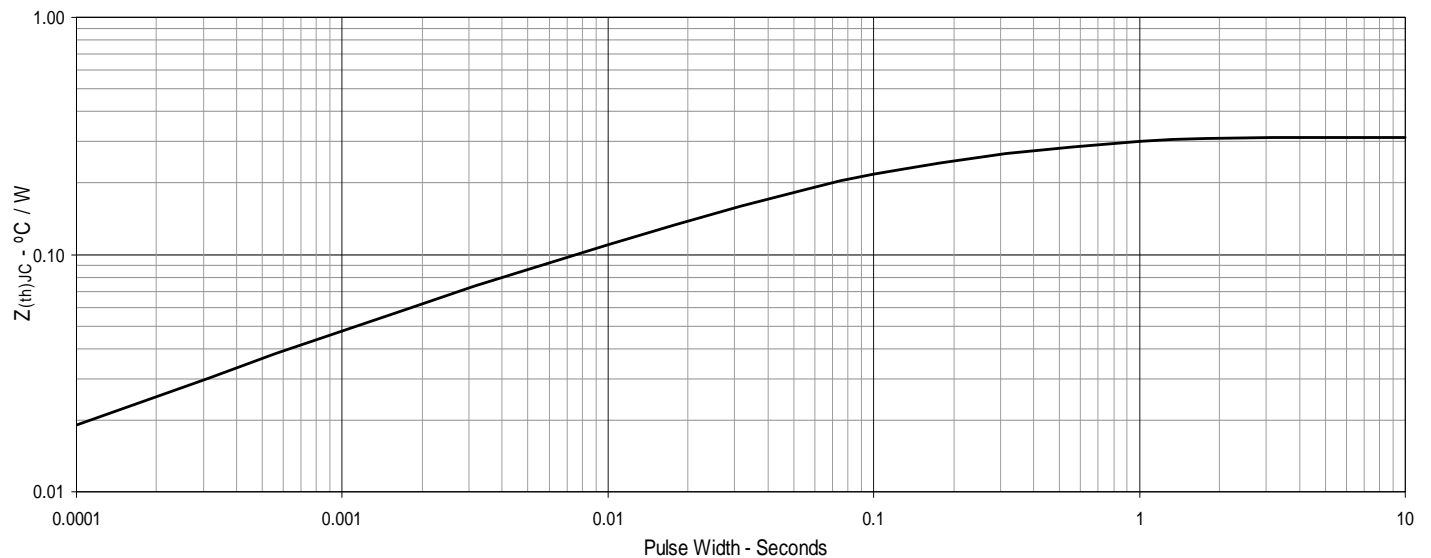
**Fig. 13. Forward-Bias Safe Operating Area**  
@  $T_C = 25^\circ\text{C}$



**Fig. 14. Forward-Bias Safe Operating Area**  
@  $T_C = 75^\circ\text{C}$



**Fig. 15. Maximum Transient Thermal Impedance**



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